

87.64
7
15.86
52.73
25.36

DRILL CHART TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLAYED	QTY
•	12.0	+3.0/-3.0	PLAYED	58
•	12.0	+3.0/-3.0	NON-PLAYED	96
•	60.0	+3.0/-3.0	NON-PLAYED	4
⌀	126.0	+3.0/-3.0	NON-PLAYED	4

LAYER STACKUP		FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS
PRIMARY SIDE SILKSCREEN				[INCHES]
PRIMARY SIDE SOLDERMASK		1oz		
SECONDARY SIDE		1oz		0.063
SECONDARY SIDE SOLDERMASK				
SECONDARY SIDE SILKSCREEN				

SIGNATURES			DATE	TEXAS INSTRUMENTS	PROC081
LAYOUT BY	JA	050522			
REVIEWED BY	ZA	050522			
APPROVED BY	AMB	050522			
				J7X PROC081 JTAG ADAPTER BOARD	
SIZE D				Rev A	
SCALE: NONE				SHEET 1 OF 09	

FABRICATION NOTES:
1. FABRICATE PCB IN ACCORDANCE WITH IPC-6012D, CLASS 2; PER IPC-6011.
2. MATERIALS:
1. LAMINATE AND PREPREG (B-STAGE) TO BE IN ACCORDANCE WITH IPC-4101/126. (MIN TO 170)
2. COPPER FOIL TO BE IN ACCORDANCE WITH IPC-MF-150, UNLESS OTHERWISE SPECIFIED. ALL COPPER WEIGHT FOR OUTER LAYERS TO BE 35UM (1 OZ). COPPER WEIGHT IS TO BE CONSIDERED "FINISHED". THE COPPER FOIL THICKNESS TOLERANCES SHALL BE AS PER IPC-6012B TABLE NO.3-7 AND 3-8.
3. ALL HOLES SHALL BE LOCATED WITHIN 0.15MM DIAMETER OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.125MM.
4. BOW AND TWIST SHALL NOT EXCEED MORE THAN 0.75% OF THE DESIGN LENGTH.
5. CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20% FROM ITS ORIGINAL DATA. INCASE FOR MATCHING IMPEDANCE MISTRAL SHALL APPROVE THE MODIFIED WIDTHS AND SPACING. TRACE WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.
6. AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.
7. FINISH:
1. ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIG. ELECTROLESS NICKEL/IMMERSION GOLD. ELECTROLESS NICKEL SHALL BE 3-4 MICRONS. TYPICAL IMMERSION GOLD THICKNESS SHALL BE 0.04-0.06 MICRONS OF SOLDERABLE IMMERSION GOLD SURFACE.
2. APPLY LIQUID PHOTO IMAGARABLE SOLDER MASK PER IPC-99-09A, CLASS II, TO BOTH SIDES OF THE BOARD OVER BARE COPPER. VIA HOLES SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK. ONLY SOLDER MASK IMAGES THAT ARE 0.008(0.2) PER SIDE SHALL BE REDUCED IF REQUIRED. ALL OTHER SOLDER MASK IMAGES SHALL NOT BE ENLARGED. DEFAULT COLOUR OF SOLDER MASK SHALL BE GREEN.
3. SILKSCREEN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE NO SILKSCREEN ON ANY SOLDERABLE COMPONENT PAD. CLIPPING OF SILK SCREEN SHALL BE ALLOWED IF THE SILK SCREEN FALLS ON SOLDERABLE AREAS.
4. SURFACE AND VIA HOLES FINISH SHALL NOT BE LESS THAN 200UM (0.00079").
5. ALL HOLES SURROUNDED BY LAND <+0.010" SHALL BE COMPLAIN TO IPC6012, CLASS 2.
8. MARKING:
1. BOARD SHALL MEET THE REQUIREMENTS OF UL-794E WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, UL FILE NUMBER, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE RENDERED IN SILKSCREEN.
9. TEST REQUIREMENTS:
1. 100% NET LIST ELECTRICAL VERIFICATION USING MISTRAL SUPPLIED IPC-D-356 NET LIST FOR OPENS AND SHORTS.
10. THEIVING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.
11. TEAR DROPS SHALL BE ADDED ON VIAs AND THROUGH HOLE PADS IN OUTER LAYERS.
12. FINISHED PCB THICKNESS SHALL BE 0.063" +/-10%.
13. MIN TRACE WIDTH/SPACING ON BOARD IS 0.006"/0.006".

REVISIONS		
REV #	DESCRIPTION	DATE
REV #	CCN #	DDMMYY